

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM643541

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
THINQ TECHNOLOGIES, INC.		04/30/2021	Corporation: DELAWARE
COMMIO, LIMITED LIBILITY COMPANY		04/30/2021	Limited Liability Company: TEXAS
TELI TECHNOLOGIES, LLC		04/30/2021	Limited Liability Company: DELAWARE
RECEIVING PARTY DATA			
Name:	Silicon Valley Bank, as Administrative Agent		
Street Address:	3003 Tasman Drive, HF 150		
City:	Santa Clara		
State/Country:	CALIFORNIA		
Postal Code:	95054		
Entity Type:	Corporation: CALIFORNIA		
PROPERTY NUMBERS Total: 3			
Property Type	Number	Word Mark	
Registration Number:	4965216	THINQ	
Serial Number:	90481963	COMMIO	
Serial Number:	88926622	TELI	
CORRESPONDENCE DATA			
Fax Number:	8004947512		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	202-370-4756		
Email:	ipteam@cogencyglobal.com		
Correspondent Name:	Jay daSilva		
Address Line 1:	1025 Vermont Ave NW, Suite 1130		
Address Line 2:	COGENCY GLOBAL INC.		
Address Line 4:	Washington, D.C. 20005		
ATTORNEY DOCKET NUMBER:	1365598 TM		
NAME OF SUBMITTER:	Naomi Sakata		
SIGNATURE:	/Naomi Sakata/		

OP \$90.00 4965216

DATE SIGNED:	04/30/2021
---------------------	------------

Total Attachments: 7

- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page3.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page4.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page5.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page6.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page7.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page8.tif
- source=Trademark Filing - Intellectual Property Security Agreement - thinQ Technologies, Inc#page9.tif

INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement is entered into as of April 30, 2021 by and between the companies listed on the signature page hereto (each a “*Grantor*”) and SILICON VALLEY BANK, as administrative agent and collateral agent for the Lenders (as defined below) (in such capacities, “*Administrative Agent*”).

RECITALS

A. Administrative Agent, the Lenders and the other Secured Parties (as defined in the Credit Agreement) have agreed to make certain advances of money and to extend certain financial accommodations to THINQ TECHNOLOGIES, INC., a Delaware corporation (the “*Borrower*”) in the amounts and manner set forth in that certain Credit Agreement, dated as of April 30, 2021, by and among THINQ HOLDINGS, LLC, a Delaware limited liability company (“*Holdings*”), the Borrower, the Guarantors party thereto, the several Lenders party thereto from time to time, Administrative Agent, and Silicon Valley Bank, as Issuing Lender and Swingline Lender (as amended, restated, amended and restated, supplemented, restructured or otherwise modified from time to time, the “*Credit Agreement*”). Unless otherwise specified, capitalized terms used herein are used as defined in the Credit Agreement or the Guarantee and Collateral Agreement (as defined below), as applicable.

B. In consideration of the agreement by Administrative Agent, the Lenders and the other Secured Parties to make the financial accommodations to Borrower under the Credit Agreement, Holdings, Borrower, and each other Grantor have entered into that certain Guarantee and Collateral Agreement in favor of Administrative Agent, dated as of even date herewith (as the same may be amended, modified or supplemented from time to time, the “*Guarantee and Collateral Agreement*”).

C. The Secured Parties are willing to make such financial accommodations to Borrower, but only upon the condition, among others, that Holdings, Borrower, and each other Grantor shall grant to Administrative Agent a security interest in certain Copyrights, Trademarks, and Patents (in each case, as defined in the Guarantee and Collateral Agreement) to secure the obligations of Holdings, Borrower, and each other Grantor under the Credit Agreement and the Guarantee and Collateral Agreement.

D. Pursuant to the terms of the Credit Agreement and the Guarantee and Collateral Agreement, Holdings, Borrower, and each other Grantor have granted to Administrative Agent, for the benefit of the Secured Parties, a security interest in all of Holdings’, Borrower’s, and each other Grantor’s right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of the Secured Obligations, each Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

To secure its Obligations under the Credit Agreement and Loan Documents, each Grantor grants and pledges to Administrative Agent a security interest in all of such Grantor’s right, title and interest in, to and under its Intellectual Property collateral (including without limitation those Copyrights, Patents, and Trademarks listed on Exhibits A, B, and C hereto, respectively), and all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits) and goodwill associated therewith, the right to sue for past, present and future infringements, all rights corresponding

thereto throughout the world and all re-issues, divisions continuations, renewals, extensions and continuations-in-part thereof.

This security interest is granted in conjunction with the security interest granted to Administrative Agent under the Guarantee and Collateral Agreement, and each Grantor hereby acknowledges and agrees that the rights and remedies of Administrative Agent with respect to the security interest in the Intellectual Property collateral made and granted hereby are more fully set forth in the Guarantee and Collateral Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein. In the event of any conflict between any provision of the Guarantee and Collateral Agreement and any provision of this Intellectual Property Security Agreement, the provisions of the Guarantee and Collateral Agreement shall control.

This Intellectual Property Security Agreement may be executed by one or more of the parties to this Intellectual Property Security Agreement on any number of separate counterparts, and all of said counterparts taken together shall be deemed to constitute one and the same instrument. Delivery of an executed counterpart by electronic transmission shall be equally effective as delivery of an original executed counterpart.

THIS INTELLECTUAL PROPERTY SECURITY AGREEMENT SHALL BE GOVERNED BY, AND CONSTRUED AND INTERPRETED IN ACCORDANCE WITH, THE INTERNAL LAWS (AND NOT THE CONFLICT OF LAW RULES) OF THE STATE OF NEW YORK.

[Remainder of Page Left Intentionally Blank]

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTORS:

THINQ TECHNOLOGIES, INC.

By: _____

Name: Dominic Ang

Title: Secretary and Treasurer

COMMIO, LIMITED LIABILITY COMPANY

By: _____

Name: Dominic Ang

Title: Secretary

TELI TECHNOLOGIES, LLC

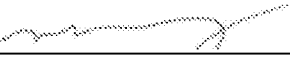
By: _____

Name: Dominic Ang

Title: Secretary

ADMINISTRATIVE AGENT:

SILICON VALLEY BANK

By: 
Name: Henry Wang
Title: Director

[Signature Page to Intellectual Property Security Agreement]

TRADEMARK
REEL: 007276 FRAME: 0066

EXHIBIT A

COPYRIGHTS

Registered Copyrights

N/A

Pending Copyright Applications

N/A

EXHIBIT B

PATENTS

Issued Patents

N/A

Pending Patent Applications

N/A

EXHIBIT C

TRADEMARKS

Registered Trademarks

<u>Grantor</u>	<u>Jurisdiction</u>	<u>Registration No.</u>	<u>Registration Date</u>	<u>Filing Date</u>	<u>Registered Owner</u>	<u>Mark</u>
thinQ Technologies, Inc.	United States	4965216	05/24/2016	07/10/2014	thinQ Technologies, Inc.	THINQ

Pending Trademark Applications

<u>Loan Party</u>	<u>Jurisdiction</u>	<u>Application No.</u>	<u>Filing Date</u>	<u>Applicant</u>	<u>Mark</u>
commio, Limited Liability Company	United States	90481963	01/22/2021	commio, Limited Liability Company	commio
Teli Technologies, LLC	United States	88926622	05/21/2020	Teli Communications, LLC	Teli

ny-2098118